

Defective pixel specification of the VD55G1

Introduction

This document provides an overview of the EWS defect specification for the VD55G1 global shutter image sensor optimized for near infrared scenes. The sensor captures up to 168 frames per second in an 804 x 704 resolution format.

The device is a 0.5 megapixels global shutter image optimized for near infrared scenes. Table below outlines key device parameters.

Table 1. Key device parameters

Parameter	Description
Pixel size	2.61 μm x 2.61 μm
Pixel resolution	808 x 708 pixels (including borders)
Die size	2.73 x 2.16 mm
Sensor technology	3D stacked
Shutter	Global
Analog gain	x1 to x8
ADC resolution	10 bits
Frame rate (at full resolution)	Up to 168 fps in 10bits full resolution
CSI-2 serial interface data rate	Up to 1.2 Gbp/s
Pixel output format	RAW8 or RAW10
Power supply (Min./Typ./Max.)	AVDD: 2.7/2.8/2.9 V VDDIO: 1.62/1.8/1.92 V DVDD: 1.05/1.1/1.26V
External clock frequency range	6 MHz to 27 MHz, DC coupled
Operating temperature (Tj)	-30°C to +85°C (functional)
Temperature sensor accuracy	$\pm 2^\circ\text{C}$ in the range [25°C; 105°C]

1 Acronyms and abbreviations

Table 2. Acronyms and abbreviations

Acronym/abbreviation	Definition
ADC	analog-to-digital converter
AVDD	analog supply voltage (VDDA)
DVDD	digital supply voltage (Vcore)
EWS	electrical wafer sort
fps	frames per second
LED	light emitting diode
LSB	least significant bit
ppm	parts per million
VDDIO	IO supply voltage

2 Test conditions

2.1 Voltage supplies

During defective pixel testing, the sensor used the nominal supply voltages shown in the table below.

Table 3. Nominal supply voltages

Supply voltage	Value used
DVDD	1.2 V
VDDIO	1.8 V
AVDD	2.8 V

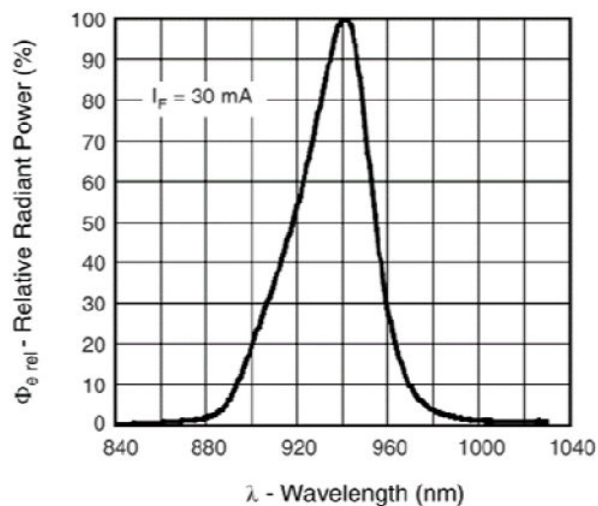
2.2 Light sources

During testing, the following LED panel with the following characteristics is used.

Table 4. Characteristics of light sources

Parameter	LED
Maximum intensity	100 $\mu\text{W}/\text{cm}^2$
Intensity accuracy	$\pm 5\%$
Light area	80 mm x 100 mm
Uniformity	$\pm 3\%$

Figure 1. Relative radiant power vs. wavelength



2.3 Temperature

The test temperature is fixed by the prober chuck at $T_{\text{Junction}} = 60^\circ\text{C}$.

2.4 Image readout and capture settings

Table 5. Image readout settings

Parameter	Setting
Full resolution	808 x 716
Visible data	804 x 704
Dark lines	8
Borders	Always on (4 rows and columns)
Defect correction	Always off

Note: All the capture settings (including dark lines, visible data, and the borders) are for a full resolution of 808x716. But, the algorithms are applied on the visible data (including the borders) only for an image resolution of 808x708.

3 Defective pixel specification

Images are captured in different lighting conditions. The images are then analyzed with a defect detection algorithm.

3.1 Capture definition

Defectivity is tested in dark and light conditions with the **image correction included in the IP deactivated**.

Table 6. Image capture settings

Parameter	Dark capture	Light capture
Light power	Off	19 $\mu\text{W}/\text{cm}^2$ ⁽¹⁾
Supplies	Nominal	Nominal
Integration time	10 ms	12 ms
Analog gain	4	1
Digital gain	1	1
Dark calibration	Off	On (with pedestal at 0)
Number of frames	16	5

1. The light capture is done using infrared light source to reach roughly 70% of the maximum code (720 LSB) in the center.

3.2 Defectivity algorithms

The purpose of this algorithm is first to detect defect pixels, then to categorize them.

The pixels that highlight significant deviation compared to a localized pixel mean can be calculated in absolute value (for captures without light) or using a percentage (for captures in light).

- Local pixels mean value are calculated using a flat kernel of 41x41.
- Each time a pixel differs from the local mean by an absolute value or a relative threshold, the pixel is identified as “failing pixel” and a corresponding fail map is generated for future fail categorization process.

Once the defect map is generated, the defect categorization algorithm sorted the failed pixels to detect single pixels, couplets, clusters, rows, and columns issues.

Figure 2. Categorization of failed pixels

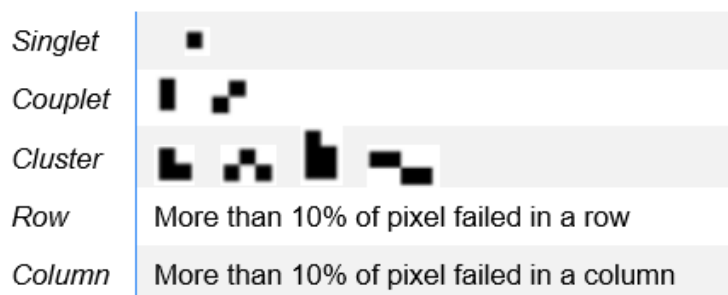
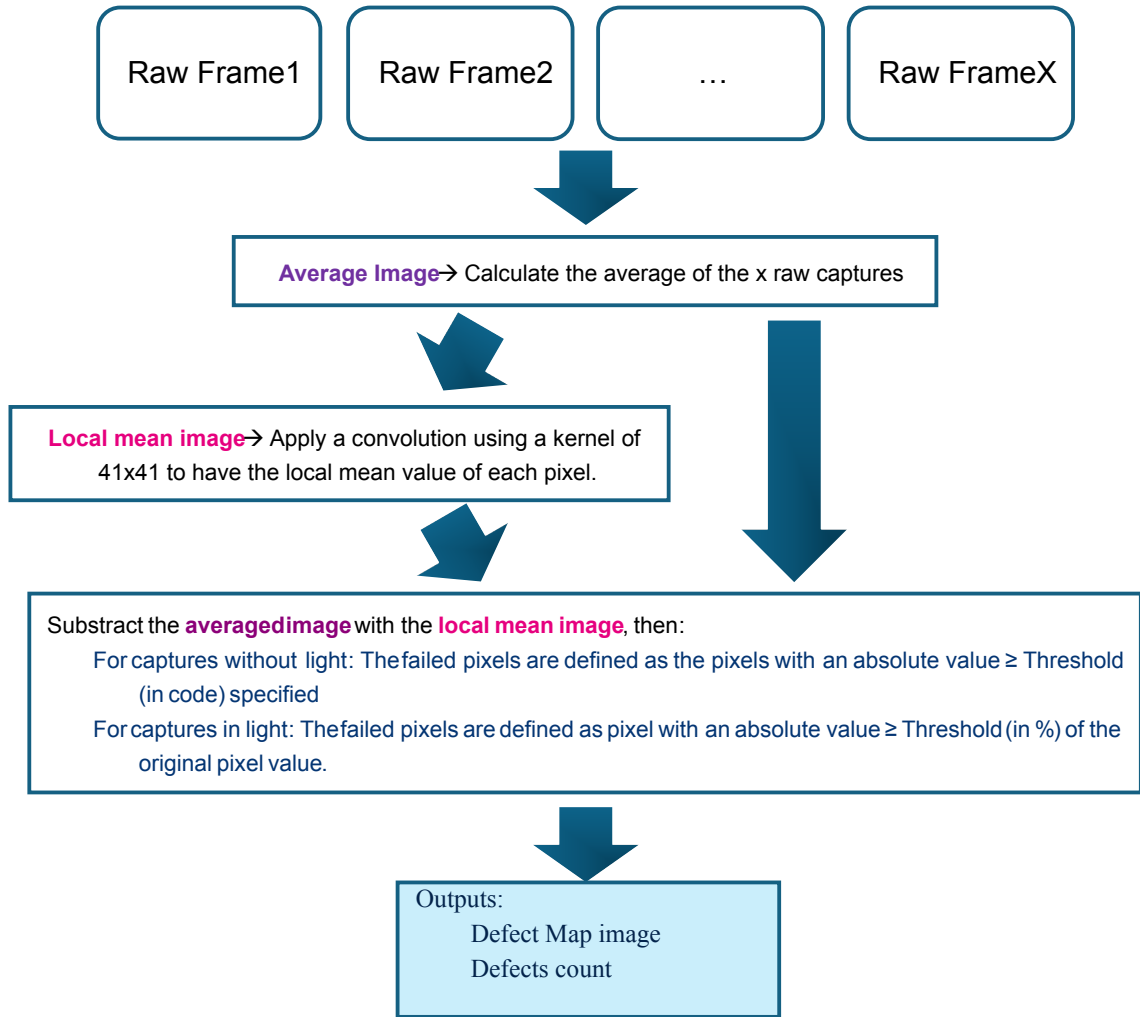


Figure 3. Defect detection implementation

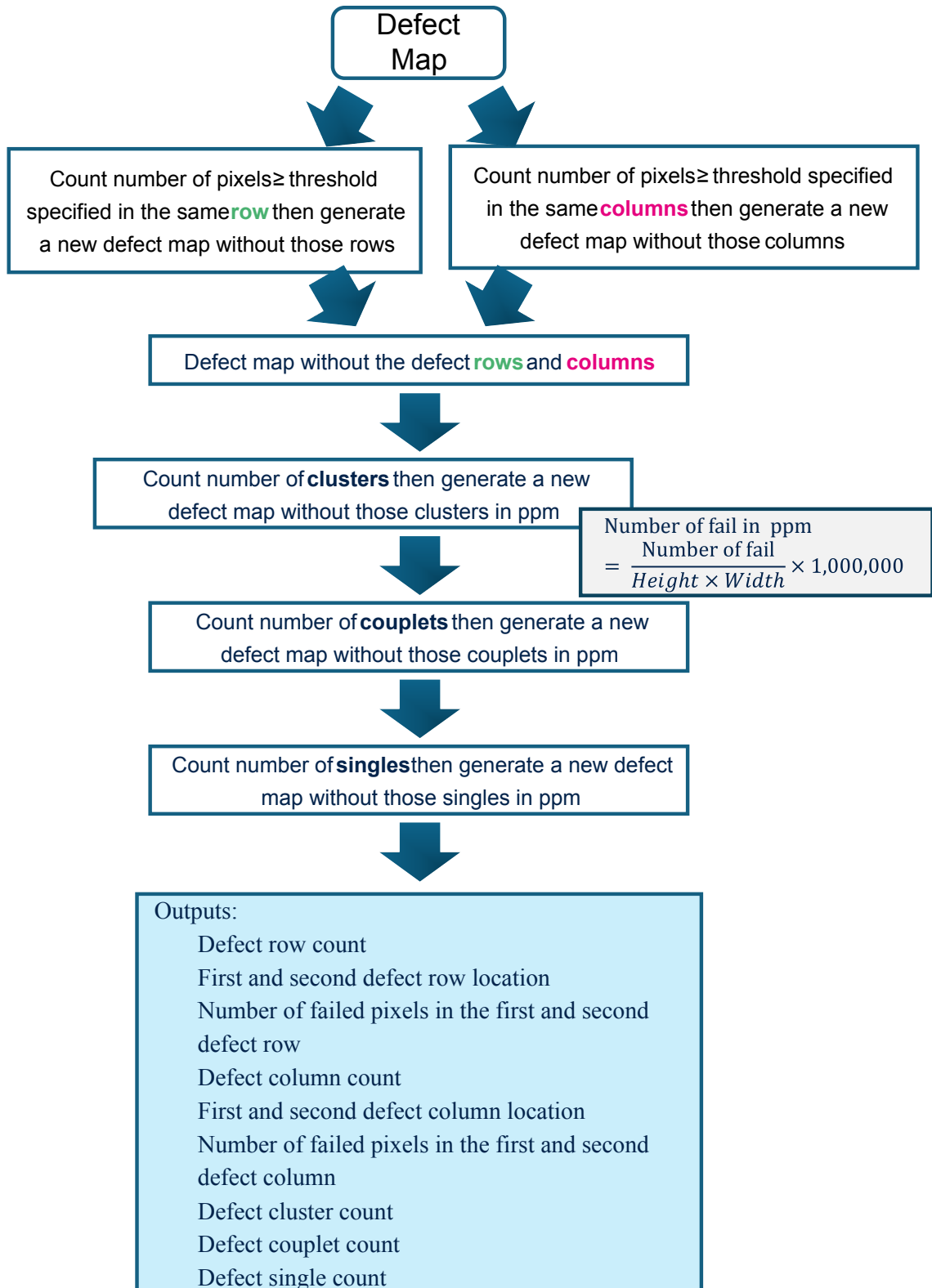


The table below shows the thresholds applied to the dark and light captures.

Table 7. Dark and light capture thresholds

Capture	Threshold applied
Dark	±25 codes
Light	±12%

Figure 4. Defect categorization



3.3 Defective limits

Table 8. Defective limits

Parameters	Max. defects in the dark	Max. defects in the light
Defective row counts	0	0
Defect column counts	0	0
Defective single counts	150 ppm	33 ppm
Defective couplet counts	20 ppm	13 ppm
Defective cluster counts	0 ppm	0 ppm

$$\text{Number of fails in ppm} = \frac{\text{Number of fails}}{\text{Height} \times \text{Width}} \times 1,000,000$$

Revision history

Table 9. Document revision history

Date	Version	Changes
27-Jun-2024	1	Initial release

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